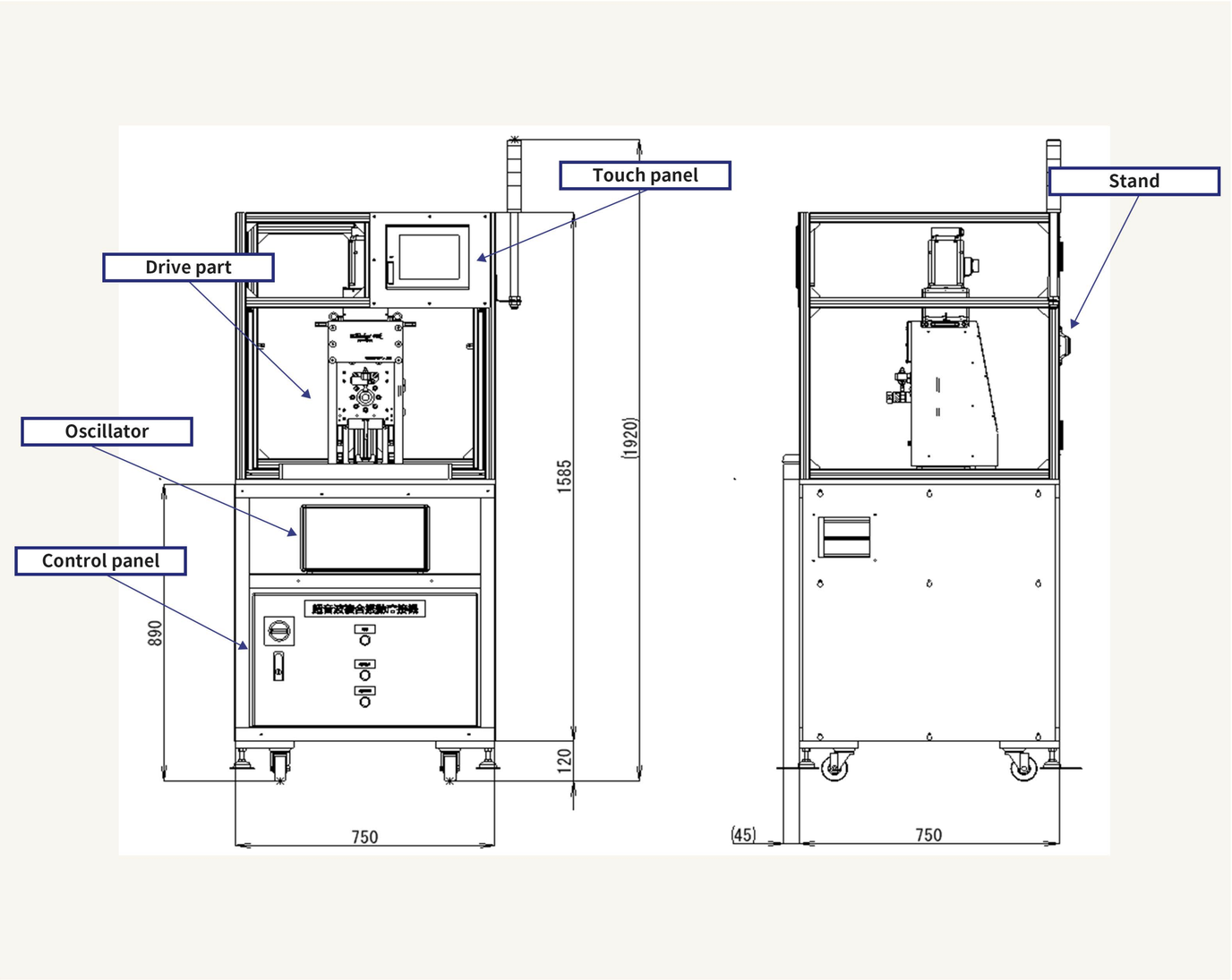
Equipment dimensions, weight, and appearance

Main unit dimensions

Drive part	Approx. W280 x D500 x H751
Control panel	Approx. W650 x D500 x H400
Oscillator	Approx. W370 x D450 x H200
Touch panel	Screen size - 8.4 inches

Main unit weight

Drive part	Approx. 45 kg
Control panel	Approx. 70 kg
Oscillator	Approx. 30 kg
Stand	Approx. 210 kg



Bonding specifications

Frequency	40 kHz (39.5 kHz ± 1 kHz)
Bonding area	Approx. 78.5 mm2 (depending on the workpiece specified by your company)
Drive system	AC servo motor (1 kW)
Control method	Position control, speed control, and push control via AC servo motor (set range: 1 to 400 N)
Target workpieces	Workpieces designated by your company (next-generation battery parts (all solid state, LIB, etc.), power semiconductor parts, etc.)
Maximum stroke	Distance from horn standby position to maximum bond depth: 40 mm (50 mm for maintenance)

Power supply, output

Power specifications for overall equipment

Supply voltage	Three-phase 200 V 50 Hz/60 Hz
Consumption current	23A
Power capacity	5.3kVA

Power specifications for drive system

Supply voltage	Three-phase 200 V 50 Hz/60 Hz
Consumption current	13A
Power capacity	3.7kVA

Oscillator power specifications

Supply voltage	Single-phase 200 V 50 Hz/60 Hz
Consumption current	10A
Power capacity	1.6kVA
Maximum output	1000W

Note

Due to product improvements, specifications and appearance are subject to change without notice. Since products are made to order, the specifications may differ from those listed, depending on the required specifications and options. Thank you for your understanding.Due to product improvements, specifications and appearance are subject to change without notice.

Configuration and recording

Bonding time	Setting of the bonding time: 0.001 to 9.999 (s)
Pre-burst	Configuration and setting of time to be used as a guide when oscillating while moving down
Pre-shot	Setting of time and static pressure to be used as a guide during preliminary oscillation before bonding
After burst	Configuration and setting of time to be used as a guide for oscillation after bonding
Static pressure	Setting, displaying, and recording of the welding force applied to the bond: 1 to 400 (N)
Power	Displaying and recording of the power when bonding, and setting of the peak power: 1 to 1000 (W)
Energy	Calculation, recording, and setting of energy when bonding: 0.01 to 99.99 (J)
Bond depth control	• Displaying, recording, and setting of bond sample deformation (Bond dist.): 1 to 5000 (μm) • Oscillation stop due to deformation of bond material (Bond dist.): 0.001 to 9.999 (s)
Variable settings	Variable function (5 levels) for configuration and setting of static pressure to be used as a guide for oscillation during bonding
Process settings	Detailed process entry functions for driving force and oscillation (10 processes)
Threshold settings	Setting of the upper and lower limits for the OK/NG judgment (9 items)
Recipe settings	Registration function for setting bonding conditions, etc. (20 types)
Graph	Process charts (10 processes), oscillation graph (7 types), and trend graph (6 types)
Measurement data output	• SD card output in CSV format (Excel compatible) (15 items) • Data transfer via Ethernet or USB2.0 (dedicated software required) • Compatible with "GX LogViewer," a Mitsubishi Electric logging data display and analysis tool (free of charge)
Actual load detection	Piezoelectric force sensor
Conveyance equipment interface	Input/output unit and Ethernet unit are provided

Optional

Conveyance equipment interface	Addition of MELSECNET / H unit
Safety mechanism	Area sensor, signal tower, electronic door lock, and magnet catch (with limits)
Position feedback	Displacement meter
Equipment stand	Please refer to the device appearance (touch panel box can also be selected)